

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3110	pad near3 reinforc\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 20:28
L2	327889	"257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 20:28
L3	199	1 and 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 20:32
L4	4	((("6858944") or ("6825541"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/18 20:42
L5	8	((("5965903") or ("6232662") or ("3808474") or ("6551916"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/18 20:47
L6	2	("6399897").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/18 20:51
L7	2	("6890828").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/18 20:51
L8	9	("5828121"   "6057224"   "6071805"   "6204165"   "6211561"   "6268261"   "6413827"   "6555467"   "6713835").PN. OR ("6890828").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/18 20:51
L9	16	("5530290"   "5798559"   "6017814"   "6057224"   "6060381").PN. OR ("6204165").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/18 20:52

L10	18	("4899439"   "4920639"   "5126192"   "5171713"   "5256274"   "5386142"   "5567982"   "5798559"   "5828121"   "6016000"   "6033996"   "6091149"   "6184121"   "6204165"   "6255712"). PN. OR ("6596624").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/18 20:59
L11	2	("6822329").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/18 21:09
L12	2047	(257/784).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/18 21:09
L13	2714800	reinforc\$5 or anchor or crackstop or (crack near3 stop) or strength\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 21:10
L14	5010720	pad or land or contact	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 21:10
L15	59594	13 near6 14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 22:03
L16	59388	15 not (3 4 5 6 7 8 9 10 11)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 21:59
L17	13261	(257/784,773,779,786,781,698,758 or 438/612).ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 21:12

L18	551	16 and 17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 21:15
L19	6	((("6297563") or ("5739587") or ("6265313")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/18 21:33
L20	2	("6476491").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/18 21:33
L21	10	("20010036716"   "20020163083"   "6084304"   "6274935"   "6303505"   "6376353"   "6424036"   "6451681"   "6468906"   "6569767").PN. OR ("6747355").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/18 21:37
L22	22	("5502337"   "5622590"   "5641996"   "5700735"   "5736791"   "5739587"   "5939790"   "5948533"   "5986343"   "6020220"   "6078088"   "6100589"   "6108210"   "6198170"   "6207550"   "6218736"   "6232650"   "6238599"   "6239386"   "6313540"   "6362531"   "6365970").PN. OR ("6740985").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/18 21:38
L23	28	("5229642"   "5751065"   "5847466").PN. OR ("6100589").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/18 21:40
L24	10	("4060828"   "6027999").PN. OR ("6306749").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/18 21:50
L25	13	("5383093"   "5554940"   "5686759"   "5726458"   "5734187"   "5760429"   "5760477").PN. OR ("5917197").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/18 21:53
L26	58830	15 not (3 4 5 6 7 8 9 10 11 18 19 20 21 22 23 24 25)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 22:04
L27	32204	13 near3 14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 22:04

L28	31634	27 not (3 4 5 6 7 8 9 10 11 18 19 20 21 22 23 24 25)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 22:04
L29	1579	28 and ("438"/\$ or "257"/\$).cccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/18 22:42

## Inventor Name Search Result

Day : Sunday  
Date: 9/18/2005  
Time: 20:31:45



## Inventor Name Search Result

Your Search was:

Last Name = YAO

First Name = CHIH-HSIANG

Application#	Patent#	Status	Date Filed	Title	Inventor Name
<u>10269219</u>	<u>6759342</u>	150	10/11/2002	METHOD OF AVOIDING DIELECTRIC ARCING	YAO, CHIH-HSIANG
<u>10322412</u>	<u>6787484</u>	150	12/17/2002	METHOD OF REDUCING VISIBLE LIGHT INDUCED ARCING IN A SEMICONDUCTOR WAFER MANUFACTURING PROCESS	YAO, CHIH-HSIANG
<u>10322691</u>	<u>6812069</u>	150	12/17/2002	METHOD FOR IMPROVING SEMICONDUCTOR PROCESS WAFER CMP UNIFORMITY WHILE AVOIDING FRACTURE	YAO, CHIH-HSIANG
<u>10448656</u>	<u>6831365</u>	150	05/30/2003	METHOD AND PATTERN FOR REDUCING INTERCONNECT FAILURES	YAO, CHIH-HSIANG
<u>10455849</u>	Not Issued	41	06/06/2003	Structure for reducing stress-induced voiding in an interconnect of integrated circuits	YAO, CHIH-HSIANG
<u>10602147</u>	<u>6864701</u>	150	06/24/2003	TEST PATTERNS FOR MEASUREMENT OF EFFECTIVE VACANCY DIFFUSION AREA	YAO, CHIH-HSIANG
<u>10602751</u>	Not Issued	161	06/24/2003	Hybrid copper/low k dielectric interconnect integration method and device	YAO, CHIH-HSIANG
<u>10602970</u>	<u>6787803</u>	150	06/24/2003	TEST PATTERNS FOR MEASUREMENT OF LOW-K DIELECTRIC CRACKING THRESHOLDS	YAO, CHIH-HSIANG
<u>10706156</u>	Not Issued	61	11/12/2003	Integration film scheme for copper / low-k interconnect	YAO, CHIH-HSIANG
<u>10716682</u>	<u>6927498</u>	150	11/19/2003	BOND PAD FOR FLIP CHIP PACKAGE	YAO, CHIH-HSIANG
<u>10731983</u>	Not Issued	71	12/10/2003	Structure and method for reinforcing a bond pad on a chip	YAO, CHIH-HSIANG
<u>10742240</u>	Not Issued	71	12/18/2003	Chip orientation and attachment method	YAO, CHIH-HSIANG
<u>10761004</u>	Not	41	01/20/2004	Semiconductor chip singulation method	YAO, CHIH-HSIANG

	Issued				
<a href="#">10780512</a>	Not Issued	60	02/17/2004	Non-repeated and non-uniform width seal ring structure	YAO, CHIH-HSIANG
<a href="#">10908142</a>	Not Issued	30	04/28/2005	Multiple Etch-Stop Layer Deposition Scheme and Materials	YAO, CHIH-HSIANG
<a href="#">10940504</a>	Not Issued	30	09/13/2004	Seal ring structure for integrated circuit chips	YAO, CHIH-HSIANG
<a href="#">10979408</a>	Not Issued	30	11/02/2004	Bond pad structure with stress-buffering layer capping interconnection metal layer	YAO, CHIH-HSIANG
<a href="#">11018604</a>	Not Issued	30	12/21/2004	Test patterns for measurement of effective vacancy diffusion area	YAO, CHIH-HSIANG
<a href="#">11196184</a>	Not Issued	30	08/03/2005	Methods for enhancing die saw and packaging reliability	YAO, CHIH-HSIANG
<a href="#">60477713</a>	Not Issued	159	06/11/2003	Hybrid copper/ low k dielectric interconnect integration method and device	YAO, CHIH-HSIANG

Inventor Search Completed: No Records to Display.

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Last Name	First Name
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**Inventor Name Search Result**

Your Search was:

Last Name = HUANG

First Name = TAI-CHUN

Application#	Patent#	Status	Date Filed	Title	Inventor Name
<a href="#">09292742</a>	6211574	150	04/16/1999	SEMICONDUCTOR PACKAGE WITH WIRE PROTECTION AND METHOD THEREFOR	HUANG, TAI-CHUN
<a href="#">09323904</a>	6229702	150	06/02/1999	BALL GRID ARRAY SEMICONDUCTOR PACKAGE HAVING IMPROVED HEAT DISSIPATION EFFICIENCY, OVERALL ELECTRICAL PERFORMANCE AND ENHANCED BONDING CAPABILITY	HUANG, TAI-CHUN
<a href="#">09366637</a>	6369439	150	08/04/1999	STRIP OF SEMICONDUCTOR PACKAGE	HUANG, TAI-CHUN
<a href="#">10267769</a>	6825541	150	10/09/2002	BUMP PAD DESIGN FOR FLIP CHIP BUMPING	HUANG, TAI-CHUN
<a href="#">10284715</a>	6858944	150	10/31/2002	BONDING PAD METAL LAYER GEOMETRY DESIGN	HUANG, TAI-CHUN
<a href="#">10353554</a>	Not Issued	41	01/29/2003	Bonding pad and via structure design	HUANG, TAI-CHUN
<a href="#">10448656</a>	6831365	150	05/30/2003	METHOD AND PATTERN FOR REDUCING INTERCONNECT FAILURES	HUANG, TAI-CHUN
<a href="#">10602147</a>	6864701	150	06/24/2003	TEST PATTERNS FOR MEASUREMENT OF EFFECTIVE VACANCY DIFFUSION AREA	HUANG, TAI-CHUN
<a href="#">10602751</a>	Not Issued	161	06/24/2003	Hybrid copper/low k dielectric interconnect integration method and device	HUANG, TAI-CHUN
<a href="#">10602970</a>	6787803	150	06/24/2003	TEST PATTERNS FOR MEASUREMENT OF LOW-K DIELECTRIC CRACKING THRESHOLDS	HUANG, TAI-CHUN
<a href="#">10706156</a>	Not Issued	61	11/12/2003	Integration film scheme for copper / low-k interconnect	HUANG, TAI-CHUN
<a href="#">10716682</a>	6927498	150	11/19/2003	BOND PAD FOR FLIP CHIP PACKAGE	HUANG, TAI-CHUN
<a href="#">10731983</a>	Not Issued	71	12/10/2003	Structure and method for reinforcing a bond pad on a chip	HUANG, TAI-CHUN

<a href="#">10742240</a>	Not Issued	71	12/18/2003	Chip orientation and attachment method	HUANG, TAI-CHUN
<a href="#">10761004</a>	Not Issued	41	01/20/2004	Semiconductor chip singulation method	HUANG, TAI-CHUN
<a href="#">10780512</a>	Not Issued	60	02/17/2004	Non-repeated and non-uniform width seal ring structure	HUANG, TAI-CHUN
<a href="#">10908142</a>	Not Issued	30	04/28/2005	Multiple Etch-Stop Layer Deposition Scheme and Materials	HUANG, TAI-CHUN
<a href="#">10940504</a>	Not Issued	30	09/13/2004	Seal ring structure for integrated circuit chips	HUANG, TAI-CHUN
<a href="#">10979408</a>	Not Issued	30	11/02/2004	Bond pad structure with stress-buffering layer capping interconnection metal layer	HUANG, TAI-CHUN
<a href="#">11018604</a>	Not Issued	30	12/21/2004	Test patterns for measurement of effective vacancy diffusion area	HUANG, TAI-CHUN
<a href="#">11196184</a>	Not Issued	30	08/03/2005	Methods for enhancing die saw and packaging reliability	HUANG, TAI-CHUN
<a href="#">60477713</a>	Not Issued	159	06/11/2003	Hybrid copper/ low k dielectric interconnect integration method and device	HUANG, TAI-CHUN

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